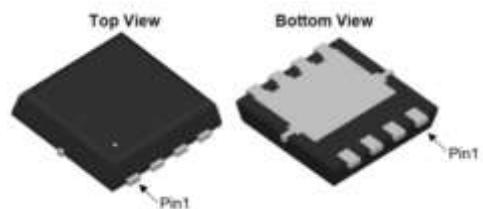


30V_{DS}/±20V_{GS} N-Channel Enhancement Mode MOSFET

Features

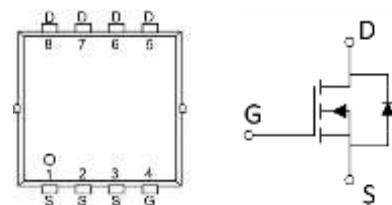
- V_{DS}=30V, I_D=100A
- R_{DS(ON)}=3mΩ (TYP.) V_{GS}=10V
- R_{DS(ON)}=5.5mΩ (TYP.) V_{GS}=4.5V
- Reliable and Rugged
- Avalanche Rated
- Low On-Resistance
- High Current Capability

PDFN3333



Applications

- Load Switch
- Power management in portable/desktop PCs
- DC/DC conversion



Ordering Information

Device	Package	Marking	Package Qty.
AGM303AP	PDFN3333	Pb-Free	5000pcs/Reel

Absolute Maximum Ratings (T_C=25°C,unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V _{GS} =0V)	V _{DS}	30	V
Gate-Source Voltage (V _{GS} =0V,static)	V _{GS}	±20	V
Continuous Drain Current (T _C =25°C)	I _D	100	A
Continuous Drain Current (T _C =100°C)		60	A
Pulsed Drain Current	I _{DM}	300	A
Single Pulsed Avalanche Energy	E _{AS}	150	mJ
Maximum Power Dissipation (T _C =25°C)	P _D	31.7	W
Operating,Storage Temperature Range	T _J ,T _{STG}	-55~150	°C

Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance,Junction-to-Case	R _{θJC}	-	3.94	-	°C/W
Thermal Resistance,Junction-to-Ambient	R _{θJA}	-	83	-	°C/W

Electrical Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V_{DSS}	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=30V, V_{GS}=0V$	-	-	1	μA
Gate -Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.6	2.5	V
Drain-Source On-stage Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	-	2.5	3.0	$m\Omega$
		$V_{GS}=4.5V, I_D=20A$	-	4.3	5.5	

Dynamic Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Input capacitance	C_{iss}	$V_{DS}=15V$	-	3499	-	pF
Output capacitance	C_{oss}		-	499	-	
Reverse transfer capacitance	C_{rss}		-	430	-	
Gate Resistance	R_g	$f=1MHz$	-	4.0	-	Ω
Total Gate Charge	Q_g		-	69	-	nC
Gate Source Charge	Q_{gs}		-	10	-	
Gate Drain Charge	Q_{gd}	$I_D=20A$	-	17	-	ns
Turn-on delay Time	$t_{d(on)}$		-	12	-	
Rise time	t_r		-	119	-	
Turn-off delay Time	$t_{d(off)}$	$R_L=0.75\Omega$	-	59	-	
Fall time	t_f		-	109	-	

Reverse Diode Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Body Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=1A$	-		1.2	V
Reverse Recovery Time	t_{rr}	$V_{GS}=0V, I_{SD}=20A$	-	-	-	ns
Reverse Recovery Charge	Q_{rr}	$d_i/d_t=500A/\mu s$	-	-	-	nC

Electrical Characteristics Diagrams

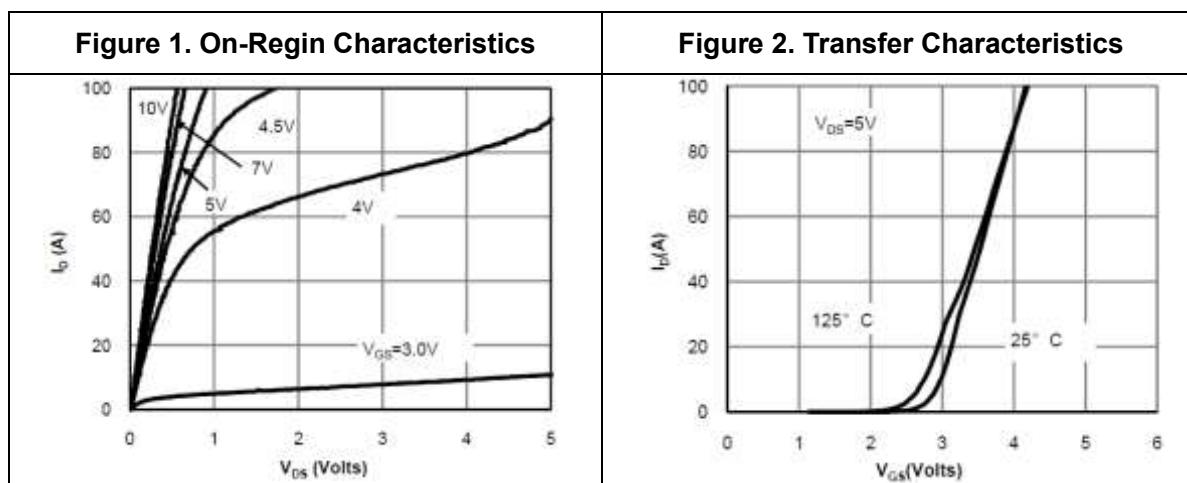


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

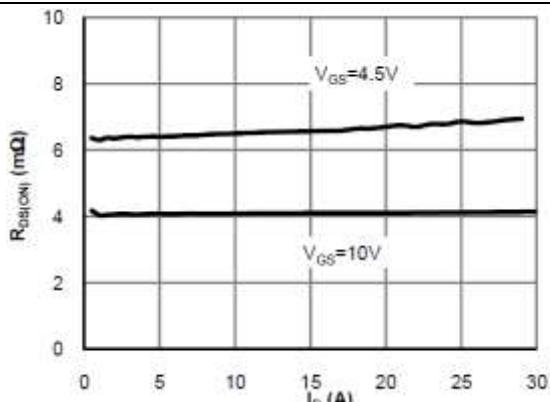


Figure 4. On-Resistance vs. Junction Temperature

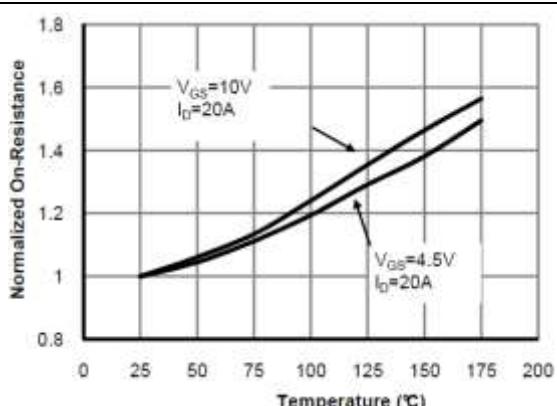


Figure 5. On-Resistance vs. Gate-Source Voltage

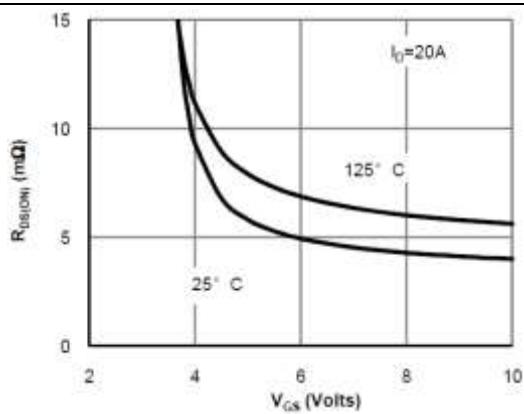


Figure 6. Body-Diode Characteristics

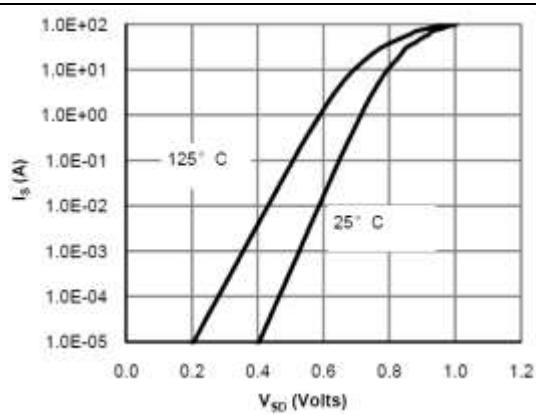


Figure 7. Gate-Charge Characteristics

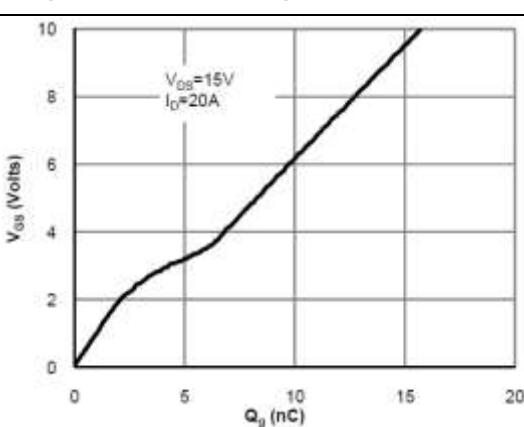


Figure 8. Capacitance Characteristics

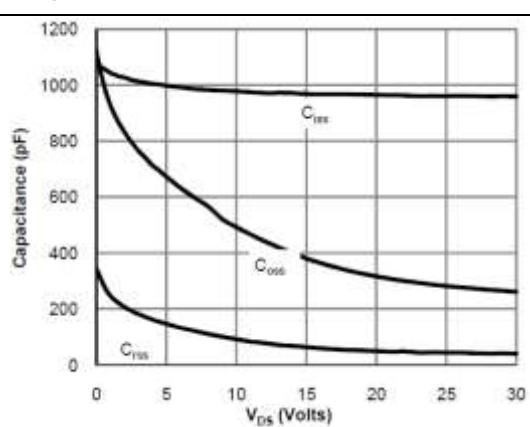


Figure 9. Maximum Forward Biased Safe Operating Area

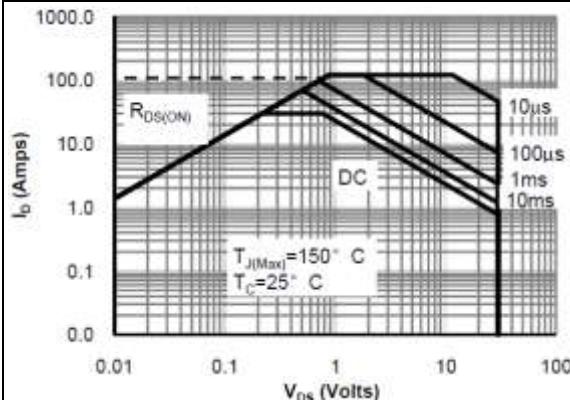


Figure 10. Single Pulse Power Rating Junction-to-Case

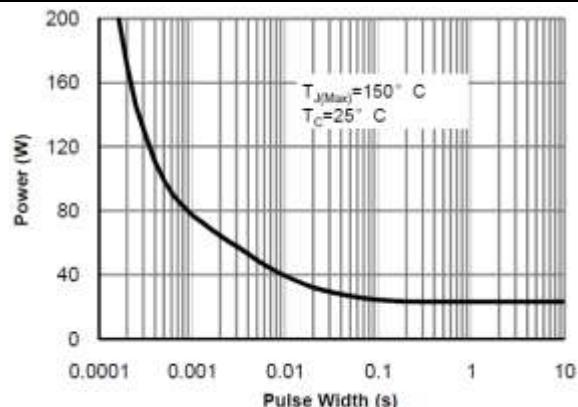


Figure 11. Normalized Maximum Transient Thermal Impedance

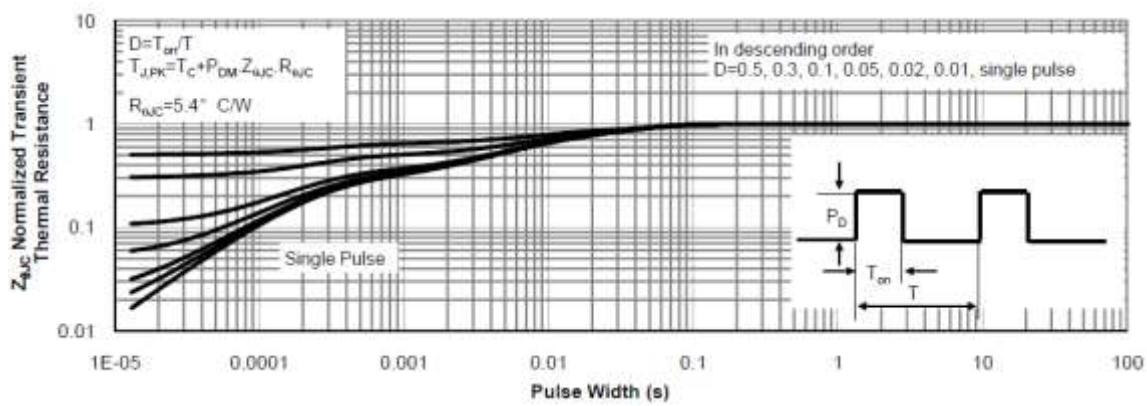


Figure 12. Power De-rating

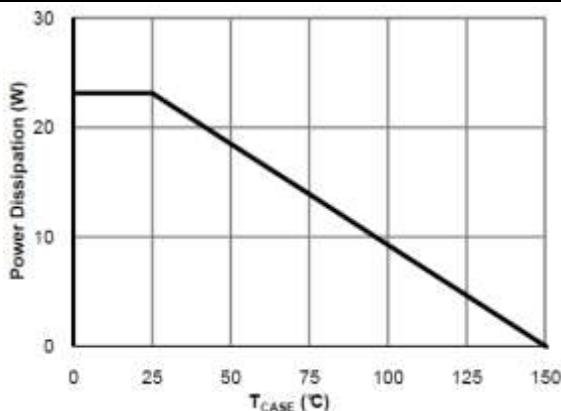


Figure 13. Current De-rating

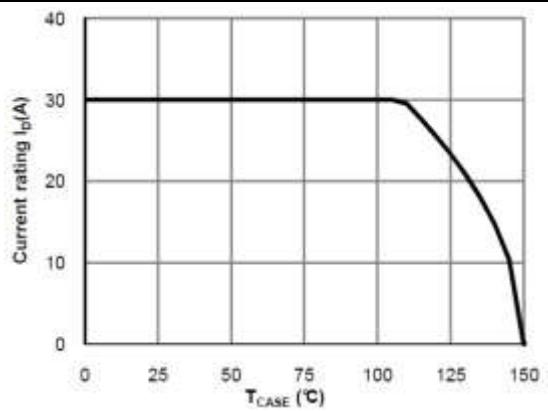


Figure 14. Single Pulse Power Rating Junction-to-Ambient

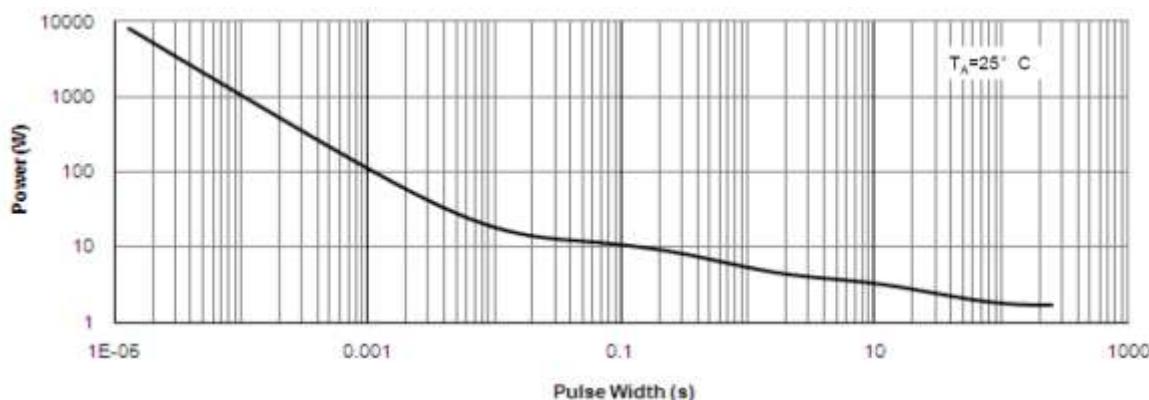
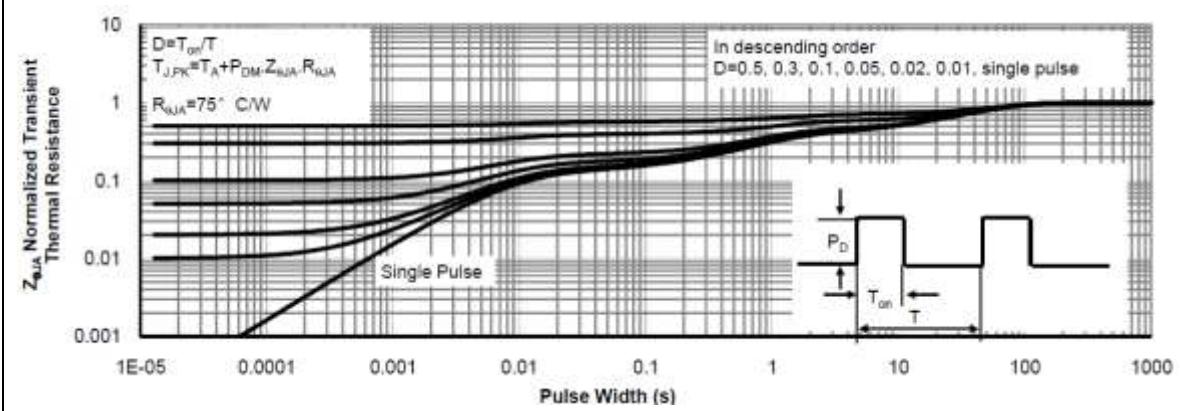


Figure 15. Normalized Maximum Transient Thermal Impedance



< Copyright >

All the Patent, Copyright and IP contained in this document belong to HAMOS, shall not be reproduced, copied, or used in other ways without permission.